

Amendments to the Specification

At page 5, please amend the paragraphs starting at line 16 and ending at line 25 as follows:

The present invention employs the following a method for manufacturing a semiconductor device, processing system and semiconductor device in order to solve the above problems.

Namely, a first aspect of the present invention is to provide A a method for manufacturing a semiconductor device comprising: forming an N region and P region on a substrate, forming wiring so as to connect one or both of ~~these~~ the N and P regions; and performing a processing step on a semiconductor substrate on which the upper surface of said wiring is exposed using a liquid, wherein said processing step is performed in a state in which the wavelength of light radiated onto said semiconductor substrate is 500 nm to less than 1 μ m.